

**KEPAMID® 2350GB**

PA66-GB50

Korea Engineering Plastics Co. Ltd.

<b>Processing/Physical Characteristics</b>	<b>Value</b>	<b>Unit</b>	<b>Test Standard</b>
<b>ISO Data</b>			
Molding shrinkage, parallel	0.5	%	ISO 294-4, 2577
<b>Mechanical properties</b>			
<b>ISO Data</b>			
Tensile Strength	75	MPa	ISO 527
Strain at break	3.5	%	ISO 527
Flexural modulus, 23°C	5350	MPa	ISO 178
Charpy notched impact strength, +23°C	3.5	kJ/m <sup>2</sup>	ISO 179/1eA
Rockwell hardness	R117	-	ISO 2039-2
<b>Thermal properties</b>			
<b>ISO Data</b>			
Melting temperature, 10°C/min	260	°C	ISO 11357-1/-3
Burning behav. at thickness h	HB	class	IEC 60695-11-10
Thickness tested	0.8	mm	-
<b>Electrical properties</b>			
<b>ISO Data</b>			
Relative permittivity, 1MHz	4	-	IEC 62631-2-1
<b>Other properties</b>			
Humidity absorption	0.5	%	Sim. to ISO 62
Density	1550	kg/m <sup>3</sup>	ISO 1183
<b>Processing Recommendation Injection Molding</b>			
Pre-drying - Temperature	80 - 90	°C	-
Pre-drying - Time	4 - 8	h	-
Processing humidity	≤0.05	%	-
Mold temperature	70 - 90	°C	-
Feed temperature	60 - 80	°C	-
Zone 1	280	°C	-
Zone 2	285	°C	-
Zone 3	285	°C	-
Nozzle temperature	290	°C	-
Screw speed	80 - 120	rpm	-
Back pressure	0.5 - 1	MPa	-

**Characteristics****Processing**

Injection Molding

**Regional Availability**

North America, Europe, Asia Pacific

**Applications**

Automotive, Electrical and Electronical